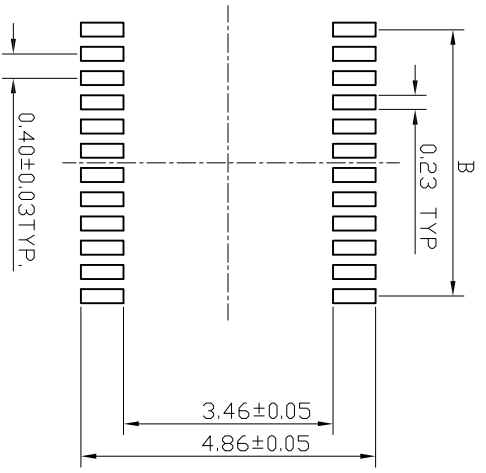
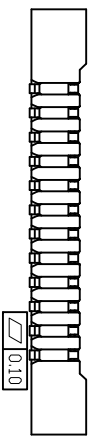
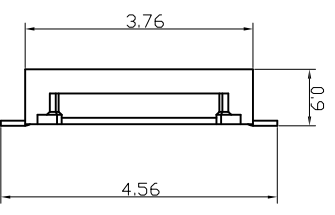
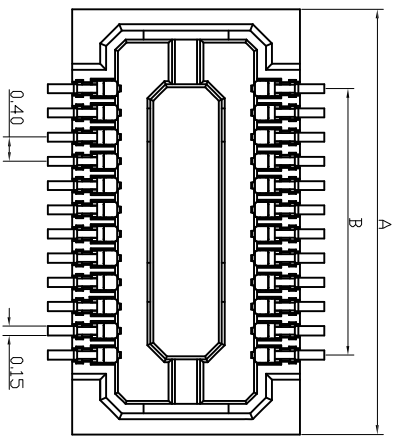


REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	CHANGER



RECOMMEND PCB LAYOUT
 DEFAULT TOL:±0.05

Dimension: mm

PIN	A	B
24	7.02	4.40
30	8.22	5.60
40	10.22	7.60
50	12.22	9.60
60	14.22	11.60

- Specifications:**
- 1) Material:**
 1-1. Molded portion: LCP resin (U94 V-0)
 1-2. Contact and Post: Copper alloy.
- 2) Surface treatment:**
 2-1. Terminal portion: Base: Ni plating Surface: Au plating (except the terminal tips) ; Exposed nickel portions.
 2-2. Metal clips: Base: Ni plating Surface: Au flash plating (except the terminal tips) ; Ni plating Surface: Sn flash plating (except the terminal tips)
- 3) Characteristics:**
 3-1. Rated voltage: 60V AC/DC
 3-2. Rated current: 0.3A/contact (Max. 5A at total contact)
 3-3. Insulation resistance: Min. 1000MΩ (initial)
 3-4. Breakdown voltage: 150V AC for 1 min.
 3-5. Saltwater spray resistance (header and socket mated): 24 hours, insulation resistance min. 100MΩ, contact resistance max. 90mΩ
- 3-6. Contact resistance: Max. 90mΩ
 3-7. Ambient temperature: -55°C~+85°C
 3-8. Storage temperature: -55°C~+85°C (product only); -40°C~+50°C (emboss packing)
 3-9. Composite insertion force: Max. 0.981N/contacts x contacts (initial)
 3-10. Composite removal force: Min. 0.165N/contacts x contacts
 3-11. Post holding force: Min. 0.49N/contacts
 3-12. Insertion and removal life: 50 times

GENERAL TOLERANCE	X, ± 1°
X ±	X ±
X ± 0.30	X ±
XX ± 0.20	XX ±
.XXX ± 0.10	.XXX ±

鍍創科技有限公司
TRONTEK TECHNOLOGY CO., LTD.
 TITLE: 0.40mm PITCH Board To Board 0.9H

CUSTOMER DRAWING	PART NO.	DWG NO.
APPROVED Kevin	B0409WVF-S-XXP	20120418
CHECKED: Paul	SCALE: 1:1	SHEET: 1 / 3
DRAWN: frank	UNIT: mm	REV: B